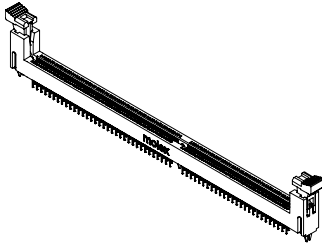


1.00mm (.039") Pitch Fully Buffered DIMM Socket

48206
Vertical



Features and Benefits

- Accepts JEDEC MO-256 module for 100% industry compatibility
- Dual ejector latches for easy module removal with features to minimize micro motion
- Beveled metal pin provides PCB retention during and after soldering
- Enables hot plug and hot swap
- Simple through-hole design supports low-cost board assembly process

Reference Information

Product Specification: PS-48206-001
Packaging: Tray
Mates With: JEDEC MO-256 modules
Designed In: Millimeters

Electrical

Voltage: 30V
Current: 0.5A
Contact Resistance: 20 milliohms max.
Dielectric Withstanding Voltage: 500V AC
Insulation Resistance: 1000 Megohms min.

Mechanical

Insertion Force to PCB: 66.64N
Mating Force: 98.00N
Unmating Force: 2.94N
Durability: 10 cycles

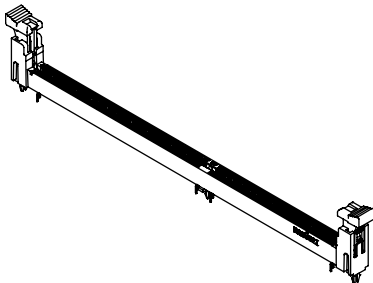
Physical

Housing: Glass-filled PA polyimide (nylon), UL 94V-0
Contact: Phosphor Bronze
Plating: Contact Area—See table
Solder Tail Area—100μm Tin
Underplating: 50μm Nickel
PCB Thickness: 1.60mm (.062")

Circuits	Order No.	Housing	Latch Color	Plating Contact	PC Tail Length	Lead-free
240	48206-0001	Nylon 4/6, Glass-Filled	White	15μm Gold	2.67mm (.105")	Yes
	48206-0002			30μm Gold	2.67mm (.105")	
	48206-0003			15μm Gold	3.18mm (.125")	
	48206-0004			30μm Gold	3.18mm (.125")	
	48206-0005			Gold Flash	2.67mm (.105")	
	48206-0006			Gold Flash	3.18mm (.125")	
	48206-0101		Black	15μm Gold	2.67mm (.105")	
	48206-0102			30μm Gold	2.67mm (.105")	
	48206-0103			15μm Gold	3.18mm (.125")	
Circuits	Order No.	Housing	Latch Color	Plating Contact	PC Tail Length	Lead-free
240	48206-0104	Nylon 4/6, Glass-Filled	Black	30μm Gold	3.18mm (.125")	Yes
	48206-0105			Gold Flash	2.67mm (.105")	
	48206-0106			Gold Flash	3.18mm (.125")	
	48206-9001			15μm Gold	2.67mm (.105")	
	48206-9002			30μm Gold	2.67mm (.105")	
	48206-9003	Nylon 6/6, Glass-Filled	White	15μm Gold	3.18mm (.125")	
	48206-9004			15μm Gold	3.18mm (.125")	
	48206-9005			30μm Gold	3.18mm (.125")	
	48206-9006			Gold Flash	2.67mm (.105")	
				Gold Flash	3.18mm (.125")	

1.00mm (.039") Pitch Fully Buffered DIMM Socket

78061/87917/87977



Features and Benefits

- High-temperature thermoplastic housing withstands lead-free solder processing
- 100% industry compatibility
- Dual ejector latches ensure easy module insertion and removal with minimal micro motion
- Built in end key design ensures correct insertion of fully-buffered memory module
- Forklocks provide proper socket to PCB alignment and retention during and after soldering

Reference Information

Product Specification: PS-78061-001, PS-87917-001
Packaging: Tray
UL File No.: E29179 (87917)
CSA File No.: LR19980 (87917)
Mates With: 1.27mm (0.5") thickness module card
Designed In: Millimeters

Electrical

Voltage: 30V AC (mc)/DC
Current: 1.0A
Contact Resistance: 30 milliohms max.
Dielectric Withstanding Voltage: 500V AC
Insulation Resistance: 1000 Megohms min.
Voltage Key: 1.8V center

Mechanical

Contact Retention to Housing: Contact—3N min.
Forklock—13N min.

Insertion Force to PCB: 66.5N
Mating Force: 87917—205.0N max.
78061—179.5N max.

Latch Actuation Force: 44N
Durability: 25 Cycles

Physical

Housing: See table
Contact: Copper Alloy
Plating: Contact Area—See table
Solder Tail Area—Tin
Underplating: Nickel
Operating Temperature: -55 to +85°C

Circuits	Order No.		Entry	Mounting	Housing	PCB Thickness	Latch Color	Lead-free
	0.38μm (15μ") Gold	0.76μm (30μ") Gold						
240	78061-0001	78061-0011	Vertical	Through Hole	Black glass-filled nylon, UL 94V-0	1.60mm (.063")	Off-white	Yes
	78061-0002	78061-0012				2.40 mm (.094")	Black	
	78061-0051	78061-0061				1.60mm (.063")		
	78061-0052	78061-0062				2.40 mm (.094")		
	87917-0001	87917-0062				1.60mm (.063")	Off-white	
	87917-0012	87917-0011	28.5° Angle	Through Hole	Black glass-filled LCP, UL 94V-0	2.40 mm (.094")	Off-white	
	87977-0021	87977-0051				3.30mm (.130")		
	87977-9001							
		Vertical Press-Fit	Black glass-filled nylon, UL 94V-0		Off-white			
					Black			